

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An optical interconnection circuit between chips, comprising:
 - a substrate;
 - a first element having a light emitting function provided on the substrate by an adhesive;
 - a second element having a light receiving function provided on the substrate by an adhesive;
 - an optical wave-guide that optically connects the first element and the second element with each other, and that includes an optical wave-guide member formed on the substrate, the optical wave-guide being in physical contact with and covering at least a part of a light receiving part of the second element; element, wherein an optical signal not only enters the second element, but also passes over the second element enabling the optical signal to be almost simultaneously sent from the first element to the second element; and
 - an electrode provided on the substrate and connected to at least one of the first element and the second element.
2. (Previously Presented) The optical interconnection circuit between chips according to claim 1,
 - the optical wave-guide being in contact with and covering at least a part of a light emitting part of the first element; and
 - the electrode being a bonding pad which is a wiring electrode for an integrated circuit chip mounted onto the substrate.

3. (Original) The optical interconnection circuit between chips according to claim 1,
the electrode being a bonding pad in a case of an integrated circuit chip being flip-chip mounted onto the substrate.

4. (Original) The optical interconnection circuit between chips according to claim 2,

further including a bump composed of a convex conductive member and formed on the integrated circuit chip, the bump being electrically connected to at least one of an input terminal and an output terminal of the integrated circuit chip, and being bonded to the electrode.

5. (Previously Presented) The optical interconnection circuit between chips according to claim 1,

a plurality of integrated circuit chips being mounted onto the substrate; and
a signal being transmitted among the plurality of integrated circuit chips via at least the first element, the second element, and the optical wave-guide.

6. (Previously Presented) The optical interconnection circuit between chips according to claim 1, further comprising additional second elements optically connected to the optical wave-guide.

7. (Previously Presented) The optical interconnection circuit between chips according to claim 1,

the first element emitting light which is to be a clock signal.

8. (Currently Amended) An optical interconnection circuit between chips, comprising:

a substrate;

a plurality of first elements having a light emitting function fixed on the substrate by an adhesive;

a plurality of second elements having a light receiving function fixed on the substrate by an adhesive;

a plurality of optical wave-guides that include an optical wave-guide member formed on the substrate; and

a plurality of integrated circuit chips that are mounted onto the substrate,
the plurality of integrated circuit chips including an integrated circuit to time control and an integrated circuit to provide driving,

at least one of the plurality of optical wave-guides provided between the integrated circuit to time control and the integrated circuit to provide driving, and

the at least one of the plurality of optical wave-guides optically connecting at least one of the plurality of first elements and at least one of the plurality of second elements, wherein an optical signal not only enters at least one of the plurality of second elements, but also passes over the at least one of the plurality of the second elements enabling the optical signal to be almost simultaneously sent from at least one of the first elements to the at least one of the second elements while being transmitted to another one of the plurality of second elements.

9. (Previously Presented) The optical interconnection circuit between chips according to claim 8,

further including a plurality of the integrated circuits to provide driving, at least one of the plurality of optical wave-guides being provided for each of the plurality of the integrated circuits to provide driving.

10. (Previously Presented) The optical interconnection circuit between chips according to claim 9,

the integrated circuit to time control being connected to a number of the plurality of first elements that is larger than the number of the integrated circuits to provide driving.

11. (Previously Presented) The optical interconnection circuit between chips according to claim 8,

the integrated circuit to provide driving being electrically connected to at least one of the plurality of second elements.

12. (Original) The optical interconnection circuit between chips according to claim 1,

the optical wave-guide being treated to prevent extraneous light from entering the optical wave-guide.

13. (Previously Presented) The optical interconnection circuit between chips according to claim 8,

the plurality of first elements emitting a light having at least two kinds of wavelengths that are different from each other to the plurality of optical wave-guides.

14. (Previously Presented) The optical interconnection circuit between chips according to claim 1,

the optical wave-guide including a light scattering mechanism scattering a light emitted by the first element.

15. (Original) The optical interconnection circuit between chips according to claim 14,

the light scattering mechanism being composed of a resin into which a light scattering particle is mixed.

16. (Original) The optical interconnection circuit between chips according to claim 14,

the light scattering mechanism being composed of a resin of which a surface is processed to include an irregularity thereon.

17. (Original) The optical interconnection circuit between chips according to claim 14,

the light scattering mechanism being composed of the optical wave-guide member of which at least one of the line width and the height differ from the other.

18. (Original) The optical interconnection circuit between chips according to claim 14,

the light scattering mechanism being composed of at least one of a resin and a glass in which a light scattering particle is dispersed, and being dome-shaped.

19. (Original) An electrooptical device, comprising:

the optical interconnection circuit between chips according to claim 1.

20. (Previously Presented) An electronic equipment, comprising:

the optical interconnection circuit between chips according to claim 1.